Media Resistant and High Temperature Accuracy Integrated Silicon Pressure Sensor for Measuring Absolute Pressure, On-Chip Signal Conditioned, Temperature Compensated and Calibrated

Motorola's MPXAZ6115A series sensor integrates on-chip, bipolar op amp circuitry and thin film resistor networks to provide a high output signal and temperature compensation. The small form factor and high reliability of on-chip integration make the Motorola pressure sensor a logical and economical choice for the system designer.

The MPXAZ6115A series piezoresistive transducer is a state–of–the–art, monolithic, signal conditioned, silicon pressure sensor. This sensor combines advanced micromachining techniques, thin film metallization, and bipolar semiconductor processing to provide an accurate, high level analog output signal that is proportional to applied pressure.

Figure 1 shows a block diagram of the internal circuitry integrated on a pressure sensor chip.

Features

- Resistant to High Humidity and Common Automotive Media
- Improved Accuracy at High Temperature
- 1.5% Maximum Error over 0° to 85°C
- Ideally suited for Microprocessor or Microcontroller–Based Systems
- Temperature Compensated from -40° to +125°C
- Durable Thermoplastic (PPS) Surface Mount Package

Application Examples

- Aviation Altimeters
- Industrial Controls
- Engine Control/Manifold Absolute Pressure (MAP)
- Weather Station and Weather Reporting Devices







MPXAZ6115A

SERIES

SMALL OUTLINE PACKAGE

PIN NUMBER					
1	N/C	5	N/C		
2	V _S	6	N/C		
3	Gnd	7	N/C		
4	V _{out}	8	N/C		

NOTE: Pins 1, 5, 6, 7, and 8 are internal device connections. Do not connect to external circuitry or ground. Pin 1 is denoted by the notch in the lead.

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MPXAZ6115A SERIES

MAXIMUM RATINGS⁽¹⁾

Parametrics	Symbol	Value	Units
Maximum Pressure (P1 > P2)	P _{max}	400	kPa
Storage Temperature	T _{stg}	-40° to $+125^{\circ}$	°C
Operating Temperature	T _A	-40° to $+125^{\circ}$	°C
Output Source Current @ Full Scale Output ⁽²⁾	l _o +	0.5	mAdc
Output Sink Current @ Minimum Pressure Offset ⁽²⁾	I ₀ –	-0.5	mAdc

NOTES:

1. Exposure beyond the specified limits may cause permanent damage or degradation to the device.

2. Maximum Output Current is controlled by effective impedance from Vout to Gnd or Vout to VS in the application circuit.

OPERATING CHARACTERISTICS ($V_S = 5.0 \text{ Vdc}$, $T_A = 25^{\circ}\text{C}$ unless otherwise noted, P1 > P2.)

Characterist	tic	Symbol	Min	Тур	Max	Unit
Pressure Range		P _{OP}	15	—	115	kPa
Supply Voltage ⁽¹⁾		Vs	4.75	5.0	5.25	Vdc
Supply Current		Ι _ο	—	6.0	10	mAdc
Minimum Pressure Offset ⁽²⁾ @ $V_S = 5.0$ Volts	(0 to 85°C)	V _{off}	0.133	0.200	0.268	Vdc
Full Scale Output ⁽³⁾ @ V _S = 5.0 Volts	(0 to 85°C)	V _{FSO}	4.633	4.700	4.768	Vdc
Full Scale Span ⁽⁴⁾ @ V _S = 5.0 Volts	(0 to 85°C)	V _{FSS}	4.433	4.500	4.568	Vdc
Accuracy ⁽⁵⁾	(0 to 85°C)	—	—	—	±1.5	%V _{FSS}
Sensitivity		V/P	—	45.9	—	mV/kPa
Response Time ⁽⁶⁾		t _R	_	1.0	—	ms
Warm–Up Time ⁽⁷⁾		—	_	20	—	ms
Offset Stability ⁽⁸⁾			_	±0.25	_	%V _{FSS}

NOTES:

1. Device is ratiometric within this specified excitation range.

2. Offset (Voff) is defined as the output voltage at the minimum rated pressure.

3. Full Scale Output (V_{FSO}) is defined as the output voltage at the maximum or full rated pressure.

 Full Scale Span (V_{FSS}) is defined as the algebraic difference between the output voltage at full rated pressure and the output voltage at the minimum rated pressure.

5. Accuracy is the deviation in actual output from nominal output over the entire pressure range and temperature range as a percent of span at 25°C due to all sources of error including the following:

• Linearity: Output deviation from a straight line relationship with pressure over the specified pressure range.

Temperature Hysteresis: Output deviation at any temperature within the operating temperature range, after the temperature is cycled to and from the minimum or maximum operating temperature points, with zero differential pressure applied.

• Pressure Hysteresis: Output deviation at any pressure within the specified range, when this pressure is cycled to and from minimum or maximum rated pressure at 25°C.

• TcSpan: Output deviation over the temperature range of 0° to 85°C, relative to 25°C.

• TcOffset: Output deviation with minimum pressure applied, over the temperature range of 0° to 85°C, relative to 25°C.

6. Response Time is defined as the time for the incremental change in the output to go from 10% to 90% of its final value when subjected to a specified step change in pressure.

7. Warm-up Time is defined as the time required for the product to meet the specified output voltage after the pressure has been stabilized.

8. Offset Stability is the product's output deviation when subjected to 1000 cycles of Pulsed Pressure, Temperature Cycling with Bias Test.



Figure 2 illustrates the absolute sensing chip in the basic Small Outline chip carrier (Case 482).

Figure 3 shows a typical application circuit (output source current operation).



Figure 4. Output versus Absolute Pressure

Figure 4 shows the sensor output signal relative to pressure input. Typical minimum and maximum output curves are shown for operation over 0 to 85°C temperature range. The output will saturate outside of the rated pressure range.

A gel die coat isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the sensor diaphragm. The gel die coat and durable polymer package provide a media resistant barrier that allows the sensor to operate reliably in high humidity conditions as well as environments containing common automotive media. Contact the factory for more information regarding media compatibility in your specific application.

MPXAZ6115A SERIES







ORDERING INFORMATION — SMALL OUTLINE PACKAGE

Device Type	Options	Case No.	MPX Series Order No.	Packing Options	Marking
Basic Element	Absolute, Element Only	482	MPXAZ6115A6U	Rails	MPXAZ6115A
	Absolute, Element Only	482	MPXAZ6115A6T1	Tape and Reel	MPXAZ6115A
Ported Element	Absolute, Axial Port	482A	MPXAZ6115AC6U	Rails	MPXAZ6115A
	Absolute, Axial Port	482A	MPXAZ6115AC6T1	Tape and Reel	MPXAZ6115A

SURFACE MOUNTING INFORMATION

MINIMUM RECOMMENDED FOOTPRINT FOR SMALL OUTLINE PACKAGE

Surface mount board layout is a critical portion of the total design. The footprint for the semiconductor package must be the correct size to ensure proper solder connection interface between the board and the package. With the correct pad geometry, the packages will self-align when subjected to

a solder reflow process. It is always recommended to fabricate boards with a solder mask layer to avoid bridging and/or shorting between solder pads, especially on tight tolerances and/or tight layouts.



Figure 5. SOP Footprint (Case 482 and 482A)

SMALL OUTLINE PACKAGE DIMENSIONS





NOTES

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